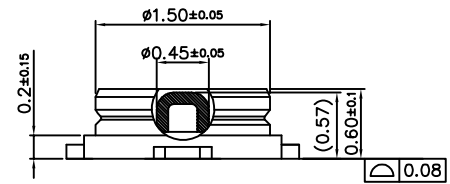
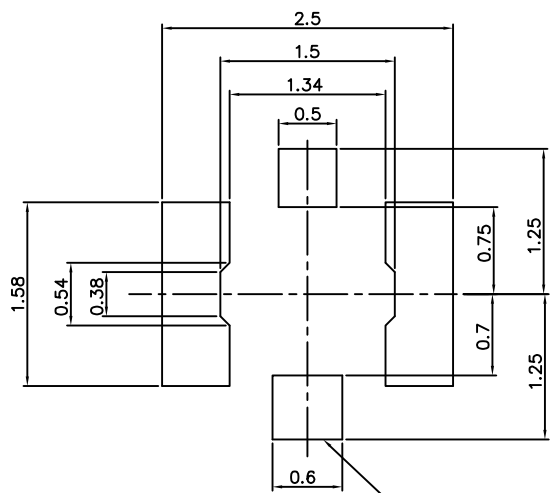
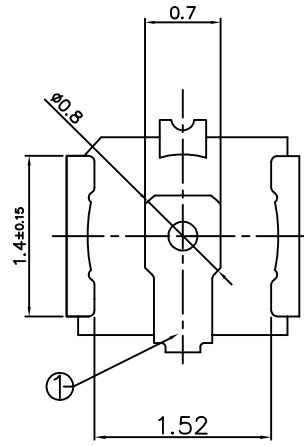
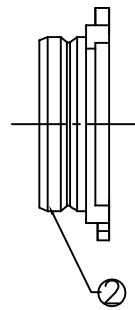
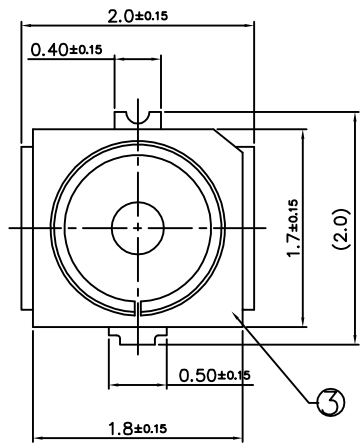


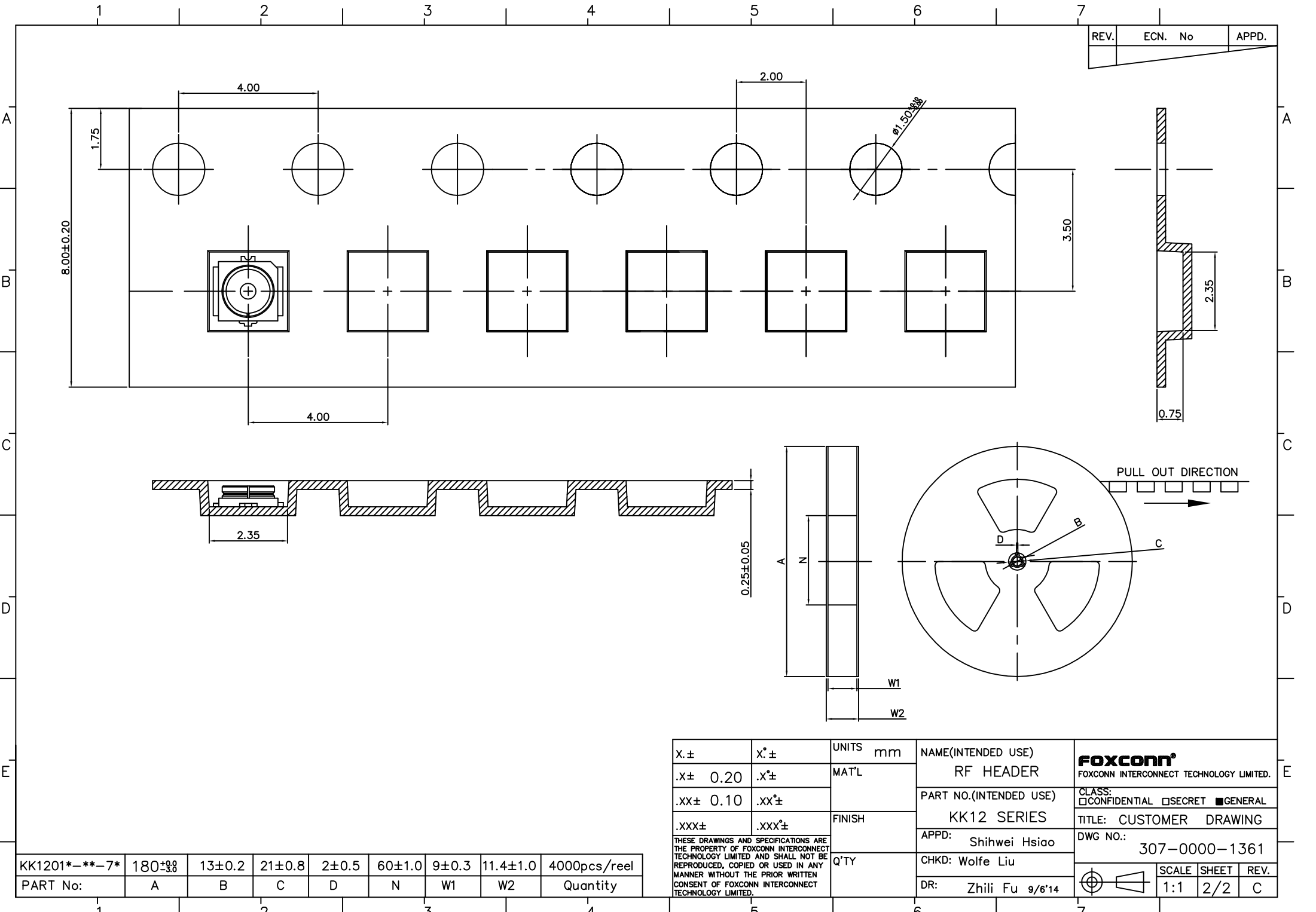
NOTES: UNLESS OTHERWISE SPECIFIED
1. DIMENSIONS SHALL BE INTERPRETED PER ASME Y14.5-2009.
2. HAMFUL MATERIAL CONTROL PLEASE FOLLOW DOC. NO. "EPI12".
3. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO
VERIFY PRODUCT DETAILS&AVAILABILITY.

REV.	ECN. No	APPD.
A	BC-07-7063888	Yihsin Chen
B	BC-11-0130287	Yihsin Chen
C	BC-14-0050297	Shihwei Hsiao



③	HOUSING	LCP
②	SHELL	SELECTIVITY PLATING
①	SIGNAL PIN	GOLD PLATING
ITEMS	DECRPTION	

X.±	X°.±	UNITS	mm	NAME(INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED. CLASS: ☐ CONFIDENTIAL ☐ SECRET ☒ GENERAL TITLE: CUSTOMER DRAWING DWG NO.: 307-0000-1361
.X± 0.20	.X°.±	MAT'L		RF HEADER	
.XX± 0.10	.XX°.±			PART NO.(INTENDED USE)	
.XXX±	.XXX°.±	FINISH		KK12 SERIES	
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				APPD: Shihwei Hsiao	SCALE SHEET REV. 1:1 1/2 C
				CHKD: Wolfe Liu	
				DR: Zhili Fu 9/6'14	
Q'TY					



REV.	ECN.	No	APPD.

X.±	X°.±	UNITS	mm	NAME(INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X± 0.20	.X°.±	MAT'L		RF HEADER	
.XX± 0.10	.XX°.±			PART NO.(INTENDED USE)	
.XXX±	.XXX°.±	FINISH		KK12 SERIES	
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				APPD: Shihwei Hsiao	CLASS: ☐ CONFIDENTIAL ☐ SECRET ☒ GENERAL
				CHKD: Wolfe Liu	TITLE: CUSTOMER DRAWING
				DR: Zhili Fu 9/6'14	DWG NO.: 307-0000-1361
					SCALE SHEET REV. 1:1 2/2 C

KK1201*-**-7*	180±9.8	13±0.2	21±0.8	2±0.5	60±1.0	9±0.3	11.4±1.0	4000pcs/reel
PART No:	A	B	C	D	N	W1	W2	Quantity

PRODUCT SPECIFICATIONS :

1. MATERIAL AND FINISH :

1-1. HOUSING :

LCP , UL 94V-0 , COLOR BLACK

1-2. CONTACT :

COPPER ALLOY,NICKEL PLATING OVER ALL,THICKNESS 50u" MIN.
GOLD PLATING WITH RoHS COMPLIANCE OVER NICKEL

1-3. METAL SHELL :

COPPER ALLOY,Ni PLATING OVER ALL, THICKNESS 50u" MIN.
100u" MIN MATTE Sn PLATING OVER Ni FOR KK12011-*1-7*.
OR GOLD FLASH(2u" Min) PLATING OVER Ni FOR KK1201*-*2-7*.
OR 100u" MIN SILVER PLATING OVER 30u" min Ni PLATING FOR KK1201*-*3-7*.

2. RATINGS :

2-1. VOLTAGE RATING :250V r.m.s. maximum
2-2. CURRENT RATING :1 Amp MAX.

3. ELECTRICAL :

3-1 .NOMINAL IMPEDANCE:50Ω
3-2. FREQUENCY RANGE:1-3GHz(VSWR 1.3MAX.),3-6GHz(VSWR 1.45MAX.)
3-3. CONTACT RESISTANCE:
CENTER CONTACT:20mΩ MAX. INITIAL; 25mΩ MAX. AFTER LIFE TEST.
OUTER CONTACT:20mΩ MAX. INITIAL; 25mΩ MAX. AFTER LIFE TEST.
3-4. INSULATION RESISTANCE : 500 MEGOHMS MIN. INITIAL.
3-5. WITHSTANDING VOLTAGE:AC 300V+/-20V r.m.s. for 1 min,
No evidence of breakdown

4. MECHANICAL:

4-1. CONTACT RETENTION FORCE: 20g MIN.
4-2. NMATING FORCE 30N MAX.
UNNMATING FORCE: 3N MIN. 20N MAX.
4-3. DURABILITY: 30 CYCLES

5. ENVIRONMENTAL:

5-1. OPERATING TEMPERATURE : -40°C TO +105°C.
5-2. HARMFUL MATERIAL PLEASE FOLLOW DOC. NO."EPI12".

6. THE CONCENTRATIONS OF Br&Cl CAN SATISFY THE REQUIREMENTS OF HALOGEN-FREE IN DOCUMENT EPI12.

B	BC-11-0130327	Yihsin Chen
A	BC077086325	Yusan
REV.	ECN NO	APPD.

FOXCONN [®] FOXCONN INTERCONNECT TECHNOLOGY LIMITED.		
APPD. : Yihsin Chen	CLASS: ☐ CONFIDENTIAL ☐ SECRET ☒ GENERAL	
CHKD. : Yu-san Hsiao	TITLE : SPECIFICATION,	
DR. : Zhili Fu 10/6'14	PROD. SERIES : KK12* SERIES	
	DWG. NO : 307-0300-1361	
	REV. : B	SHEET : 1/1

ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT	REMARK
①	HOUSING	1	LCP UL94 V-0	MOLDED BLACK COLOR	
②	CONTACT	1	COPPER ALLOY	A) NICKEL PLATING OVER ALL THICKNESS : 50 u" MIN. B) GOLD PLATING SEE NOTES BELOW	
③	SHELL	1	COPPER ALLOY	A) SELECT PLATING SEE NOTES BELOW	

NOTES:

1. PRODUCT NO. MATRIX :

KK1201*-* *-7 *

K: RF CONNECTOR	—	LEAD FREE CODE
K: SERIES CODE	—	F: LEAD FREE
TOTAL HEIGHT	—	H: HALOGEN FREE&LEAD FREE
1: 0.60MM	—	PACKAGE TYPE
CIRCULAR DIAMETER	—	7: TAPE&REEL
2: 1.50MM	—	SHELL PLATING CODE
PIN POSITION	—	02: GOLD FLASH(2u" Min) OVER Ni
01: 1PIN	—	03: SILVER(100u" Min) OVER Ni
	—	CONTACT GOLD PLATING
	—	1: GOLD FLASH(4u" MIN)
	—	3: 30u" MIN GOLD
	—	7: 15u" MIN GOLD

- HARMFUL MATERIAL PLEASE FOLLOWING FOXCONN DOC. NO. "EPI12".
- PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.
- THE CONCENTRATIONS OF Br&Cl CAN SATISFY THE REQUIREMENTS OF HALOGEN-FREE IN DOCUMENT EPI12.

C	BC-14-0051656	Shih-wei Hsiao
B	BC-11-0130337	Yihsin Chen
A	BC077086233	Yusan
REV.	ECN NO	APPD.

FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.	
APPD. : Shih-wei Hsiao	CLASS: ☐ CONFIDENTIAL ☐ SECRET ☒ GENERAL
CHKD. : Wolfe Liu	TITLE : MATERIAL SHEET
DR. : Zhili Fu 9/17'14	PROD. SERIES : KK12* SERIES
	DWG. NO : 307-0500-1361
	REV. : C SHEET : 1/1